AGENDA
10 JUNE 2024

Time	Programme		
09:45-10:00	**Registration (EU Delegation)** Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin **Meeting point: main entrance of the building**		
10:30-11:30	**TAIWAN EXPO Opening Ceremony** Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin		
11:30-12:00	**TAIWAN EXPO Guided Tour** Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin		
11:30-13:30	**Welcoming Reception** Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin		
Semiconductor Forum Location: Hotel De Rome		**EU – Taiwan Excellence Tech Show, EU-Taiwan Business Cooperation's Seminar, organised by ECCP & EEN** Location: Main Expo Stage and Taiwan Excellence Pavilion	
13:00 – 18:00	**13:00 – 13:30** **Registration & Networking** **Opening remarks** **Photo Session**	**14:00 – 18:00**	**14:00 – 16:00** **Taiwan Excellence Tech Show** Including performance, brand presentation, influencer interactive

	14:00 – 14:15 **Topic: TBD** *Mr. Gunnar C. Thomas, General Councel, EMEA, TSMC* **14:15 – 14:30** **Topic: TBD** *Dr. Christian Kotzsch, President, ESMC* **14:30 – 14:45** **Advancing the Semiconductor Ecosystem. Tackling the Industry's Biggest Challenges through Closer Collaboration** *Dr. Suresh Rajarman, Executive Vice President and Head of Thin Film Business Unit, Merck Electronics* **14:45 – 15:15** **Session II: Taiwan-EU Collaboration in Automotive or AI Semiconductors** 14:45 – 15:00 Automotive/AI Semiconductor Cooperation between EU and Taiwanese Industries *Mr. Weizhi Yu, Vice President of Automotive*		activity, lucky draw and onsite mini game, media interviews, happy hour) **16:00 -17:30** **EU-Taiwan Business Cooperation's Seminar, organised by ECCP & EEN** **16:00 -16:45** • **Pitching session** – an opportunity EU & Taiwanese organisation to present their companies and offerings. - *CASTRA, Bulgaria* - *Iconic Cluster, Romania* - *OptecBB, Germany* - *Ecodomus, Italy,* - *Southwest Hungarian Engineering Cluster, Hungary* - *Finance Innovation, France* - *BioPMed, Italy* - *Lucas Wang, Assistant Vice President of Corporate Synergy Development Center*

	Product Marketing, MediaTek 15:15 – 15:00 Semiconductors at the Heart of Decarbonization and Digitalization *Dr. Thomas Schafbauer, Executive Vice President and COO of the Connected Secure Systems Division, Infineon* **15:15 – 15:30 BREAK** **15:30 – 16:00** **Session III: Semiconductor Talent Incubation and Tech Innovation** 15:30 – 15:45 Semiconductor Sustainability and Talent Development *Mr. Terry Tsao, Global Chiev marketing Officer and President of Taiwan, SEMI* 15:45 – 16:00 Semiconductor Talent Incubation and Tech Innovation *Prof. Dr.-Ing. Albert Hauberg, Executive Director, Fraunhofer Institute for Integrated Circuits IIS* **16:00 – 16:50**		- *Larry CHEN, CEO of MIJILY CO., LTD.* - *Sammy CHIU, Vice President of Business Development of SZ JIE, Taiwan, LI ENTERPRISE CO., LTD, Taiwan* - *Deya, General Manager of UNI-PARAGON ENTERPRISE CO., LTD* **16:45 – 17:05** • **Testimonials & Success stories of cooperation** - ***Mike Richardson,*** *Senior Project Manager Optecbb* - ***Roberto LAI,*** *Deputy International Affairs Officer of ITRI Europe Office* **17:05 – 17:45** • **Practical Aspects on EU-Taiwan Business Cooperation** • ***Dr. Jürgen Maurer***, East-Asia Correspondent, *Germany Trade and Invest (GTAI)*

	Panel Discussion: Semiconductors Driving a Sustainable Future *Moderator: Mr. Terry Tsao, Global Chief marketing Officer and President of Taiwan, SEMI* - Dr. Yee-Wei Huang, Vice President & Spokesman, Realtek Semiconductor Group Corp; - Dr. Wolfgang Weber, CEO, ZVEI Frankfurt am Main, Germany - Dr. Torstein Thieme, CDO, DEAXO Gmbh and a Board Member, Silicon Saxony e.V. **16:50 – 17:10** **Q & A** **17:10 – 18:00** **Networking**		• ***Leonie Yang,*** *Acting Delegate of German Business and Head of the German Trade Office Taipei)*
19:30 – 21:00	**Networking Reception** *An exceptional opportunity to further expand collaboration opportunities between EU and Taiwan* **Place: Augustiner am Gendarmenmarkt** **Address:** Charlottenstraße 55, 10117 Berlin, Germany		

11 JUNE 2024

Time	Programme
10:00 -10:30	**Gathering of the EU Delegation** Location: ECCP & EEN Networking Zone, Exhibition Floor
10:30 – 12:00	**Matchmaking via B2match, online participants** Location: ECCP & EEN Networking Zone, Business zone
12-00 – 13:00	**Break, Free Time**
13:00 – 17:00	**Matchmaking, meetings with onsite participants** Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin
17:00 – 17:30	**Debriefing session: feedback harvesting for all EU Cluster participants.** Location: ECCP & EEN Networking Zone, Exhibition Floor • Performed by **Zoran Stamencic, EISMEA (European Commission)**

WEDNESDAY 12 JUNE 2024

SITE VISITS, organised in partnership with OpTecBB and Fraunhofer IZM

08:45 – 14:00*

Fraunhofer IZM

- Advanced packaging, Substrates, Process, Characterization, Technology Transfer

As part of the Fraunhofer-Gesellschaft, Fraunhofer IZM specializes in applied and industrial contract research. Fraunhofer IZM's focus is on packaging technology and the integration of multifunctional electronics into systems. The institute has a staff of more than 438 and saw a turnover of 39,6 million euros in 2022, of which 38,3 percent was earned through contract research. Fraunhofer IZM has two sites in Germany. Apart from its headquarters near Berlin Mitte, the institute is also represented in Dresden and Cottbus, strategically important centers for electronic development and manufacturing.

Of interest is the Semiconductor business unit

Business Unit - Semiconductors

Using 3D integration of components, complex, heterogeneous system-in-packages (SiP solutions) can be developed. The major advantages of 3D system architecture include:

- High miniaturization and improved form factor
- Improved performance and power efficiency thanks to the faster signal speeds and higher bandwidth via shorter and narrower signal paths
- Increased functionality due to heterogeneous integration of components, which are fabricated using various techno logies (sensor, memory, ASIC and transceiver)
- System partitioning
- Faster product implementation (also known as 'time to market')
- Fewer costs due parallelization of assembly processes

Fraunhofer IZM's services include a closed process chain – concept and process development, characterization, as well as reliability assessment and prototyping of 3D systems. All processes required throughout the chain for the realization of wafer-level packages, including through silicon via (TSV) formation, are available in our labs. 3D systems that meet the disparate target profiles demanded by various application scenarios, such as image sensors, sensor nodes, eGrains, can be realized and characterized. We work in close cooperation with tool and material suppliers to continuously improve applied technologies.
The Semiconductor business unit is supported by 4 departments:

The four Fraunhofer IZM departments promote internationally cutting-edge technology development. The departments jointly work on application areas and key development topics, ensuring the research is advanced across technologies. In key development topics, the Fraunhofer IZM researchers monitor and develop highly promising research questions, paving the way for future projects with industry.

Here, Fraunhofer IZM benefits from its close cooperation with the Technischen Universität Berlin and other scientific institutes. Fraunhofer IZM has cooperated on highly productive prliminary research with the TU Berlin since its establishment, and the close relationship between the institute and university is best illustrated by the current practice of appointing a joint IZM institute head and TU university professorship.

"Wafer Level System Integration" (WLSI)

The department "Wafer Level System Integration" (WLSI) develops advanced packaging and system integration technologies and offers customer-specific solutions for microelectronic products in the overall scope of smart system integration. Approx. 60 scientists work at two locations: Berlin and Dresden (ASSID: All Silicon System Integration Dresden). WLSI is cooperating globally with manufacturers and users of microelectronic products as well as cleanroom equipment producers and material developers from the chemical industry.

System Integration and Interconnection Technologies (SIIT),

The range of services provided by the department System Integration and Interconnection Technologies (SIIT), which has more than 100 employees, spans from consultation, to process development, right through to technical system solutions. Developing processes and materials for interconnection technologies on board, module and package levels and the integration of electrical, optical and power-electronic components and systems are at the forefront of our research.
We assist companies with application-oriented pre-competitive research, as well as the development of prototypes and small volume production. Our services include application advice, technology transfer and further qualification of personnel through practical training.

The Department Environmental and Reliability Engineering

New products and technologies have to comply with an increasing range of strict specifications, and at the same time have to be cost-efficient and environmentally friendly. The Department Environmental and Reliability Engineering supports technological developments until they reach market maturity with environmental and reliability analysis reaching from nano-characterisation level to evaluation and optimisation at the system level. Under the leadership of Dr. Nils F. Nissen, a unique combination is achieved between the established cross-sectional specialist fields of reliability and sustainability.

In view of worldwide extending markets and limited resources, every new generation of products and technologies must generate more functionality and assured reliability while consuming fewer resources. Without adequate reliability, the commercial success of an application is anyway endangered, and at the same time the environmental impact of typically production-intensive microelectronics increases furtherby premature failures or the need for replacements. Sustainable electronic technologies must therefore be reliable and have a low environmental impact.

The department of RF & Smart Sensor Systems

The department of RF & Smart Sensor Systems focuses on research and development of application-specific wireless sensor nodes, radar and proximity sensor systems as well as wireless communication and high-performance computing (HPC) modules for a wide range of application fields.

Furthermore, we perform in-depth characterization of electronic packaging technologies, and develop innova-tive designs for RF/high-speed, millimeter-wave (mmWave) and terahertz (THz) packaging.

Our R&D activities concentrate on the following areas:

- High-frequency Packaging
- Components and Modules for Communication (e.g. 5G/6G) and Computing
- Radar and Proximity Sensor Systems
- Wireless Sensor Nodes and Systems
- Micro Energy Storage

- Physical Design Tools and Software
- We collaborate closely with industry partners worldwide and provide cost-effective and innovative solutions at every level along the value chain, from materials to systems.

Start-A-Factory

Start-A-Factory is part of the Fraunhofer IZM Berlin and offers hardware developers from around the world a unique opportunity.
With the help of Fraunhofer's scientists, state-of-the-art equipment, and experts from the industry, we will take your idea from the planning stage to a first industrial grade prototype – as quickly and smoothly as possible.

Our experts help you with each step along the development cycle. No matter what it entails, the support you receive is tailor-made for your project and the goal is always paramount: turning your idea into a tangible, testable prototype.

Map with all locations:

https://maps.app.goo.gl/9T5MY72p2gMTWqDL8

Photos

https://photos.app.goo.gl/dmmow1HQwJEnnBZM7